

ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®

## **Material Composition Declaration**

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard <a href="http://www.ipc.org/IPC-175x">http://www.ipc.org/IPC-175x</a>

Form Type\*
Distribute

Declaration Class\* Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information			
Company Name *	Company Unique ID	Unique ID Authority	Response Date*
Fairchild Semiconductor	00-489-5751	Dun & Bradstreet	Sat, Aug 24, 2013 01:53 AM
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com
Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Ite	Mfr Item Number Mfr Item Name		Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
74AC138SCX	74AC	138SCX	SOIC-16N				INTERNAL PENANG		0.147797	g	Each
Manufacturing Process Information											
Terminal Finish	Base Alloy	J-STD-020 MSL Rating			Peak Process Body Temperature		Max Time at Peak Temperature		No Ret	No Reflow cycles	
Matte Tin (Sn)	CU Alloy		1		260 C		30 seconds			3	

<sup>\*</sup> Required Field

## **RoHS Material Composition Declaration**

Declaration Type \* Custom

RoHS Directive 2011/65/EU **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration \*

1 - Item(s) does not contain RoHS restricted substances per the definition above

Supplier Acceptance \* Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU

None

**Declaration Signature** 

Supplier Signature

DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

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## **Homogeneous Material Composition Declaration for Electronic Products**

Item/SubItem Name SOIC-16N

Component	Material	Weight (mg)	(mg) Level Substance Category Subs		Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	4.350	Supplier		Silicon	4.350	7440-21-3	29432
Die Attach	Other Organic Materials	0.440	Supplier		Acrylic Resin	0.095	54208-63-8	640
			Supplier		Silver	0.345	7440-22-4	2337
Encapsulation	Thermoplastics	93.900	В	Antimony/Antimony Compounds	Antimony Trioxide	1.878	1309-64-4	12707
			В	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	0.939	6386-73-8	6353
			Supplier		Carbon Black	0.704	1333-86-4	4765
			Supplier		Epoxy Resin	27.231	29690-82-2	184246
			Supplier		Silica, vitreous	63.148	60676-86-0	427260
Lead Frame	Copper & its alloys	46.400	Supplier		Copper	45.003	7440-50-8	304494
			Supplier		Iron	1.114	7439-89-6	7535
			Supplier		Phosphorus	0.019	7723-14-0	126
			Supplier		Silver	0.204	7440-22-4	1381
			Supplier		Zinc	0.060	7440-66-6	408
Plating	Other Nonferrous metals & alloys	2.310	Supplier		Tin	2.310	7440-31-5	15630
Wire Bond	Precious metals	0.397	Supplier		Gold	0.397	7440-57-5	2686